

AMENDMENTS TO THE CLAIMS

Claim 1 (Previously Presented): A chip module, comprising:

a semiconductor chip fixed on a main side of a planar substrate;

at least one electrically conductive connection fitted on the main side of the substrate and connected to a connecting contact of the semiconductor chip; and

a display device, which takes up, emits, reflects or partially shields electromagnetic radiation in the range of visible wavelengths, provided on the main side of the substrate and connected to the at least one electrically conductive connection,

wherein the substrate is a film which is transmissive to the radiation to permit the radiation to be taken up, emitted, reflected or partially shielded, by the display device.

Claim 2-5 (Canceled)

Claim 6 (Previously Presented): The chip module as claimed in claim 1, wherein the substrate is polyethylene terephthalate.

Claim 7 (Original): The chip module as claimed in claim 1, further comprising at least one contact area made of electrically conductive material applied on a side of the substrate opposite the main side and connected to the at least one electrically conductive connection by a plated-through-hole passing through the substrate.

Claim 8 (Previously Presented): The chip module as claimed in claim 1, wherein the semiconductor chip and/or the display device are fixed on the substrate by means of an adhesive provided with electrically conductive filler and are connected to the at least one electrically conductive connection.

